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Details	
Product Status	Active
Core Processor	S08
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	38
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-VFQFN Exposed Pad
Supplier Device Package	48-QFN-EP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc9s08aw16cfde

Chapter 11
Serial Communications Interface (S08SCIV2)

Chapter 12
Serial Peripheral Interface (S08SPIV3)

the CPU executes a STOP instruction, the MCU will not enter either of the stop modes and an illegal opcode reset is forced. The stop modes are selected by setting the appropriate bits in SPMSC2.

HCS08 devices that are designed for low voltage operation (1.8V to 3.6V) also include stop1 mode. The MC9S08AW60 Series family of devices does not include stop1 mode.

Table 3-1 summarizes the behavior of the MCU in each of the stop modes.

Table 3-1. Stop Mode Behavior

Mode	PPDC	CPU, Digital Peripherals, FLASH	RAM	ICG	ADC1	Regulator	I/O Pins	RTI
Stop2	1	Off	Standby	Off	Disabled	Standby	States held	Optionally on
Stop3	0	Standby	Standby	Off[1]	Optionally on	Standby	States held	Optionally on

1 Crystal oscillator can be configured to run in stop3. Please see the ICG registers.

3.6.1 Stop2 Mode

The stop2 mode provides very low standby power consumption and maintains the contents of RAM and the current state of all of the I/O pins. To enter stop2, the user must execute a STOP instruction with stop2 selected (PPDC = 1) and stop mode enabled (STOPE = 1). In addition, the LVD must not be enabled to operate in stop (LVDSE = 0 or LVDE = 0). If the LVD is enabled in stop, then the MCU enters stop3 upon the execution of the STOP instruction regardless of the state of PPDC.

Before entering stop2 mode, the user must save the contents of the I/O port registers, as well as any other memory-mapped registers which they want to restore after exit of stop2, to locations in RAM. Upon exit of stop2, these values can be restored by user software before pin latches are opened.

When the MCU is in stop2 mode, all internal circuits that are powered from the voltage regulator are turned off, except for the RAM. The voltage regulator is in a low-power standby state, as is the ADC. Upon entry into stop2, the states of the I/O pins are latched. The states are held while in stop2 mode and after exiting stop2 mode until a logic 1 is written to PPDACK in SPMSC2.

Exit from stop2 is done by asserting either of the wake-up pins: $\overline{\text{RESET}}$ or IRQ, or by an RTI interrupt. IRQ is always an active low input when the MCU is in stop2, regardless of how it was configured before entering stop2.

NOTE

Although this IRQ pin is automatically configured as active low input, the pullup associated with the IRQ pin is not automatically enabled. Therefore, if an external pullup is not used, the internal pullup must be enabled by setting IRQPE in IRQSC.

Upon wake-up from stop2 mode, the MCU will start up as from a power-on reset (POR) except pin states remain latched. The CPU will take the reset vector. The system and all peripherals will be in their default reset states and must be initialized.

Chapter 4
Memory

4.1 MC9S08AW60 Series Memory Map

Figure 4-1 shows the memory map for the MC9S08AW60 and MC9S08AW48 MCUs. Figure 4-2 shows the memory map for the MC9S08AW32 and MC9S08AW16 MCUs. On-chip memory in the MC9S08AW60 Series of MCUs consists of RAM, FLASH program memory for nonvolatile data storage, plus I/O and control/status registers. The registers are divided into three groups:

- Direct-page registers ($0000 through $006F)
- High-page registers ($1800 through $185F)
- Nonvolatile registers ($FFB0 through $FFBF)

High-page registers, shown in Table 4-3, are accessed much less often than other I/O and control registers so they have been located outside the direct addressable memory space, starting at $1800.

Table 4-3. High-Page Register Summary (Sheet 1 of 2)

Address	Register Name	Bit 7	6	5	4	3	2	1	Bit 0
$1800	SRS	POR	PIN	COP	ILOP	0	ICG	LVD	0
$1801	SBDFR	0	0	0	0	0	0	0	BDFR
$1802	SOPT	COPE	COPT	STOPE	—	0	0	—	—
$1803	SMCLK	0	0	0	MPE	0	MCSEL		
$1804 – $1805	Reserved	— —	— —	— —	— —	— —	— —	— —	— —
$1806	SDIDH	REV3	REV2	REV1	REV0	ID11	ID10	ID9	ID8
$1807	SDIDL	ID7	ID6	ID5	ID4	ID3	ID2	ID1	ID0
$1808	SRTISC	RTIF	RTIACK	RTICLKS	RTIE	0	RTIS2	RTIS1	RTIS0
$1809	SPMSC1	LVDF	LVDACK	LVDIE	LVDRE	LVDSE	LVDE	0[1]	BGBE
$180A	SPMSC2	LVWF	LVWACK	LVDV	LVWV	PPDF	PPDACK	—	PPDC
$180B– $180F	Reserved	— —	— —	— —	— —	— —	— —	— —	— —
$1810	DBGCAH	Bit 15	14	13	12	11	10	9	Bit 8
$1811	DBGCAL	Bit 7	6	5	4	3	2	1	Bit 0
$1812	DBGCBH	Bit 15	14	13	12	11	10	9	Bit 8
$1813	DBGCBL	Bit 7	6	5	4	3	2	1	Bit 0
$1814	DBGFH	Bit 15	14	13	12	11	10	9	Bit 8
$1815	DBGFL	Bit 7	6	5	4	3	2	1	Bit 0
$1816	DBGC	DBGEN	ARM	TAG	BRKEN	RWA	RWAEN	RWB	RWBEN
$1817	DBGT	TRGSEL	BEGIN	0	0	TRG3	TRG2	TRG1	TRG0
$1818	DBGS	AF	BF	ARMF	0	CNT3	CNT2	CNT1	CNT0
$1819– $181F	Reserved	— —	— —	— —	— —	— —	— —	— —	— —
$1820	FCDIV	DIVLD	PRDIV8	DIV5	DIV4	DIV3	DIV2	DIV1	DIV0
$1821	FOPT	KEYEN	FNORED	0	0	0	0	SEC01	SEC00
$1822	Reserved	—	—	—	—	—	—	—	—
$1823	FCNFG	0	0	KEYACC	0	0	0	0	0
$1824	FPROT	FPS7	FPS6	FPS5	FPS4	FPS3	FPS2	FPS1	FPDIS
$1825	FSTAT	FCBEF	FCCF	FPVIOL	FACCERR	0	FBLANK	0	0
$1826	FCMD	FCMD7	FCMD6	FCMD5	FCMD4	FCMD3	FCMD2	FCMD1	FCMD0
$1827– $183F	Reserved	— —	— —	— —	— —	— —	— —	— —	— —
$1840	PTAPE	PTAPE7	PTAPE6	PTAPE5	PTAPE4	PTAPE3	PTAPE2	PTAPE1	PTAPE0
$1841	PTASE	PTASE7	PTASE6	PTASE5	PTASE4	PTASE3	PTASE2	PTASE1	PTASE0
$1842	PTADS	PTADS7	PTADS6	PTADS5	PTADS4	PTADS3	PTADS2	PTADS1	PTADS0
$1843	Reserved	—	—	—	—	—	—	—	—
$1844	PTBPE	PTBPE7	PTBPE6	PTBPE5	PTBPE4	PTBPE3	PTBPE2	PTBPE1	PTBPE0
$1845	PTBSE	PTBSE7	PTBSE6	PTBSE5	PTBSE4	PTBSE3	PTBSE2	PTBSE1	PTBSE0

5.9.8 System Power Management Status and Control 1 Register (SPMSC1)

	7	6	5	4	3	2	1[1]	0
R	LVDF	0	LVDIE	LVDRE[(2)]	LVDSE[(2)]	LVDE[(2)]		BGBE
W		LVDACK						
Reset	0	0	0	1	1	1	0	0

= Unimplemented or Reserved

1 Bit 1 is a reserved bit that must always be written to 0.

2 This bit can be written only one time after reset. Additional writes are ignored.

Figure 5-10. System Power Management Status and Control 1 Register (SPMSC1)

Table 5-11. SPMSC1 Register Field Descriptions

Field	Description
7 LVDF	**Low-Voltage Detect Flag** — Provided LVDE = 1, this read-only status bit indicates a low-voltage detect event.
6 LVDACK	**Low-Voltage Detect Acknowledge** — This write-only bit is used to acknowledge low voltage detection errors (write 1 to clear LVDF). Reads always return 0.
5 LVDIE	**Low-Voltage Detect Interrupt Enable** — This read/write bit enables hardware interrupt requests for LVDF. 0 Hardware interrupt disabled (use polling). 1 Request a hardware interrupt when LVDF = 1.
4 LVDRE	**Low-Voltage Detect Reset Enable** — This read/write bit enables LVDF events to generate a hardware reset (provided LVDE = 1). 0 LVDF does not generate hardware resets. 1 Force an MCU reset when LVDF = 1.
3 LVDSE	**Low-Voltage Detect Stop Enable** — Provided LVDE = 1, this read/write bit determines whether the low-voltage detect function operates when the MCU is in stop mode. 0 Low-voltage detect disabled during stop mode. 1 Low-voltage detect enabled during stop mode.
2 LVDE	**Low-Voltage Detect Enable** — This read/write bit enables low-voltage detect logic and qualifies the operation of other bits in this register. 0 LVD logic disabled. 1 LVD logic enabled.
0 BGBE	**Bandgap Buffer Enable** — The BGBE bit is used to enable an internal buffer for the bandgap voltage reference for use by the ADC module on one of its internal channels. 0 Bandgap buffer disabled. 1 Bandgap buffer enabled.

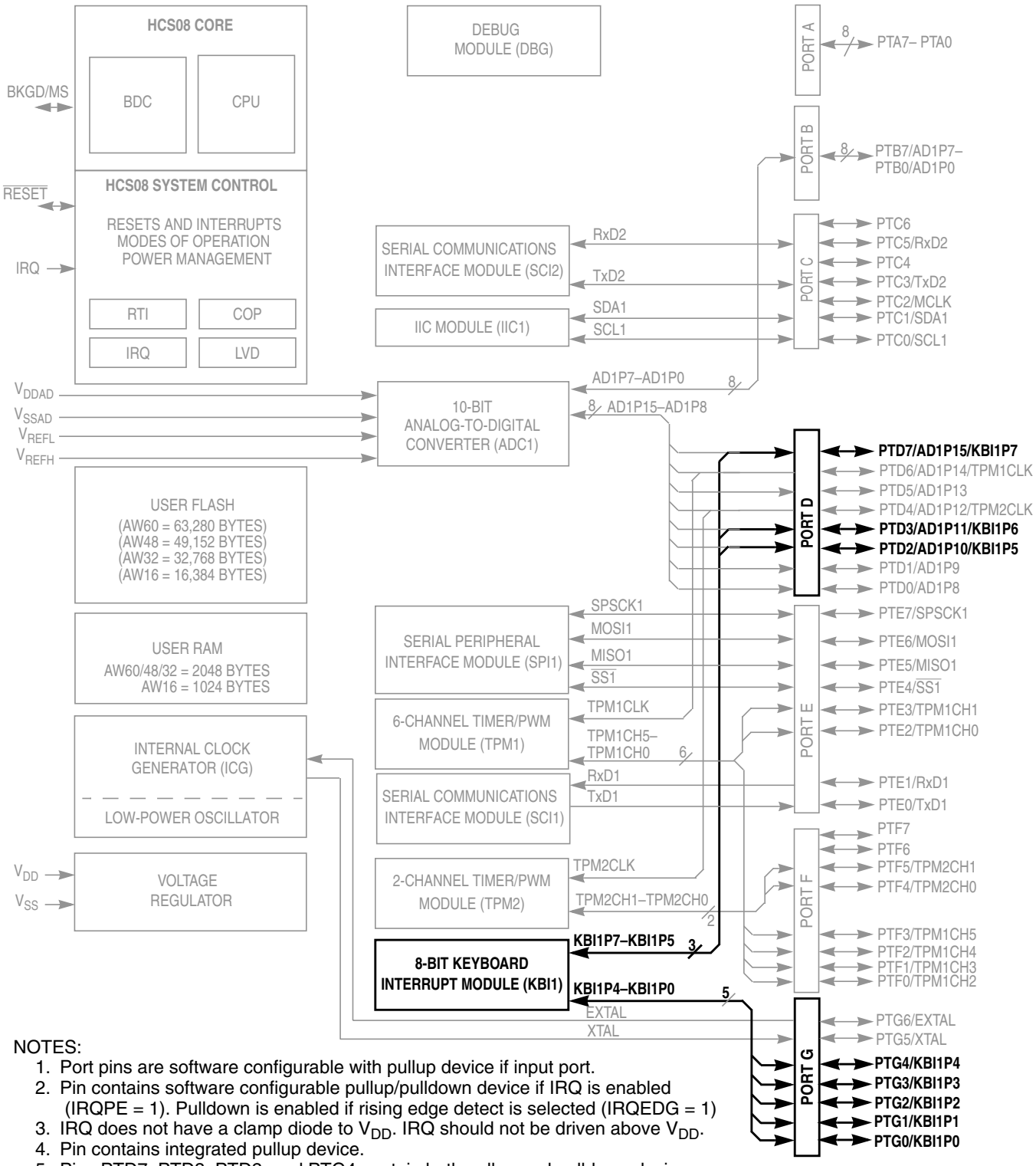
Table 7-2. HCS08 Instruction Set Summary (Sheet 3 of 7)

Source Form	Operation	Description	Effect on CCR						Address Mode	Opcode	Operand	Bus Cycles[1]
			V	H	I	N	Z	C				
BRCLR *n,opr8a,rel*	Branch if Bit *n* in Memory Clear	Branch if (Mn) = 0	–	–	–	–	–	↕	DIR (b0) DIR (b1) DIR (b2) DIR (b3) DIR (b4) DIR (b5) DIR (b6) DIR (b7)	01 03 05 07 09 0B 0D 0F	dd rr dd rr dd rr dd rr dd rr dd rr dd rr dd rr	5 5 5 5 5 5 5 5
BRN *rel*	Branch Never	Uses 3 Bus Cycles	–	–	–	–	–	–	REL	21	rr	3
BRSET *n,opr8a,rel*	Branch if Bit *n* in Memory Set	Branch if (Mn) = 1	–	–	–	–	–	↕	DIR (b0) DIR (b1) DIR (b2) DIR (b3) DIR (b4) DIR (b5) DIR (b6) DIR (b7)	00 02 04 06 08 0A 0C 0E	dd rr dd rr dd rr dd rr dd rr dd rr dd rr dd rr	5 5 5 5 5 5 5 5
BSET *n,opr8a*	Set Bit *n* in Memory	Mn ← 1	–	–	–	–	–	–	DIR (b0) DIR (b1) DIR (b2) DIR (b3) DIR (b4) DIR (b5) DIR (b6) DIR (b7)	10 12 14 16 18 1A 1C 1E	dd dd dd dd dd dd dd dd	5 5 5 5 5 5 5 5
BSR *rel*	Branch to Subroutine	PC ← (PC) + 0x0002 push (PCL); SP ← (SP) – 0x0001 push (PCH); SP ← (SP) – 0x0001 PC ← (PC) + *rel*	–	–	–	–	–	–	REL	AD	rr	5
CBEQ *oprx8,rel* CBEQA *#opr8i,rel* CBEQX *#opr8i,rel* CBEQ *oprx8*,X+,*rel* CBEQ ,X+,*rel* CBEQ *oprx8*,SP,*rel*	Compare and Branch if Equal	Branch if (A) = (M) Branch if (A) = (M) Branch if (X) = (M) Branch if (A) = (M) Branch if (A) = (M) Branch if (A) = (M)	–	–	–	–	–	–	DIR IMM IMM IX1+ IX+ SP1	31 41 51 61 71 9E61	dd rr ii rr ii rr ff rr rr ff rr	5 4 4 5 5 6
CLC	Clear Carry Bit	C ← 0	–	–	–	–	–	0	INH	98		1
CLI	Clear Interrupt Mask Bit	I ← 0	–	–	0	–	–	–	INH	9A		1
CLR *oprx8*,X CLR ,X CLR *oprx8*,SP	Clear	M ← 0x00 A ← 0x00 X ← 0x00 H ← 0x00 M ← 0x00 M ← 0x00 M ← 0x00	0	–	–	0	1	–	DIR INH INH INH IX1 IX SP1	3F 4F 5F 8C 6F 7F 9E6F	dd ff ff	5 1 1 1 5 4 6
CMP *#opr8i* CMP *opr8a* CMP *opr16a* CMP *oprx16*,X CMP *oprx8*,X CMP ,X CMP *oprx16*,SP CMP *oprx8*,SP	Compare Accumulator with Memory	(A) – (M) (CCR Updated But Operands Not Changed)	↕	–	–	↕	↕	↕	IMM DIR EXT IX2 IX1 IX SP2 SP1	A1 B1 C1 D1 E1 F1 9ED1 9EE1	ii dd hh ll ee ff ff ee ff ff	2 3 4 4 3 3 5 4
COM *oprx8*,X COM ,X COM *oprx8*,SP	Complement (One's Complement)	M ← (M̄)= 0xFF – (M) A ← (Ā) = 0xFF – (A) X ← (X̄) = 0xFF – (X) M ← (M̄) = 0xFF – (M) M ← (M̄) = 0xFF – (M) M ← (M̄) = 0xFF – (M)	0	–	–	↕	↕	1	DIR INH INH IX1 IX SP1	33 43 53 63 73 9E63	dd ff ff	5 1 1 5 4 6
CPHX *opr16a* CPHX *#opr16i* CPHX *opr8a* CPHX *oprx8*,SP	Compare Index Register (H:X) with Memory	(H:X) – (M:M + 0x0001) (CCR Updated But Operands Not Changed)	↕	–	–	↕	↕	↕	EXT IMM DIR SP1	3E 65 75 9EF3	hh ll jj kk dd ff	6 3 5 6

9.3 Features

The keyboard interrupt (KBI) module features include:

- Four falling edge/low level sensitive
- Four falling edge/low level or rising edge/high level sensitive
- Choice of edge-only or edge-and-level sensitivity
- Common interrupt flag and interrupt enable control
- Capable of waking up the MCU from stop3 or wait mode



NOTES:
1. Port pins are software configurable with pullup device if input port.
2. Pin contains software configurable pullup/pulldown device if IRQ is enabled (IRQPE = 1). Pulldown is enabled if rising edge detect is selected (IRQEDG = 1)
3. IRQ does not have a clamp diode to V_{DD}. IRQ should not be driven above V_{DD}.
4. Pin contains integrated pullup device.
5. Pins PTD7, PTD3, PTD2, and PTG4 contain both pullup and pulldown devices. Pulldown enabled when KBI is enabled (KBIPEn = 1) and rising edge is selected (KBEDGn = 1).

Figure 9-1. Block Diagram Highlighting KBI Module

11.1.1 Features

Features of SCI module include:

- Full-duplex, standard non-return-to-zero (NRZ) format
- Double-buffered transmitter and receiver with separate enables
- Programmable baud rates (13-bit modulo divider)
- Interrupt-driven or polled operation:
  - Transmit data register empty and transmission complete
  - Receive data register full
  - Receive overrun, parity error, framing error, and noise error
  - Idle receiver detect
- Hardware parity generation and checking
- Programmable 8-bit or 9-bit character length
- Receiver wakeup by idle-line or address-mark
- Optional 13-bit break character
- Selectable transmitter output polarity

11.1.2 Modes of Operation

See Section 11.3, “Functional Description,” for a detailed description of SCI operation in the different modes.

- 8- and 9-bit data modes
- Stop modes — SCI is halted during all stop modes
- Loop mode
- Single-wire mode

11.1.3 Block Diagram

Figure 11-2 shows the transmitter portion of the SCI.

Table 11-5. SCIxS1 Register Field Descriptions (continued)

Field	Description
5 RDRF	**Receive Data Register Full Flag** — RDRF becomes set when a character transfers from the receive shifter into the receive data register (SCIxD). In 8-bit mode, to clear RDRF, read SCIxS1 with RDRF = 1 and then read the SCI data register (SCIxD). In 9-bit mode, to clear RDRF, read SCIxS1 with RDRF = 1 and then read SCIxD and the SCI control 3 register (SCIxC3). SCIxD and SCIxC3 can be read in any order, but the flag is cleared only after both data registers are read. 0 Receive data register empty. 1 Receive data register full.
4 IDLE	**Idle Line Flag** — IDLE is set when the SCI receive line becomes idle for a full character time after a period of activity. When ILT = 0, the receiver starts counting idle bit times after the start bit. So if the receive character is all 1s, these bit times and the stop bit time count toward the full character time of logic high (10 or 11 bit times depending on the M control bit) needed for the receiver to detect an idle line. When ILT = 1, the receiver doesn't start counting idle bit times until after the stop bit. So the stop bit and any logic high bit times at the end of the previous character do not count toward the full character time of logic high needed for the receiver to detect an idle line. To clear IDLE, read SCIxS1 with IDLE = 1 and then read the SCI data register (SCIxD). After IDLE has been cleared, it cannot become set again until after a new character has been received and RDRF has been set. IDLE will get set only once even if the receive line remains idle for an extended period. 0 No idle line detected. 1 Idle line was detected.
3 OR	**Receiver Overrun Flag** — OR is set when a new serial character is ready to be transferred to the receive data register (buffer), but the previously received character has not been read from SCIxD yet. In this case, the new character (and all associated error information) is lost because there is no room to move it into SCIxD. To clear OR, read SCIxS1 with OR = 1 and then read the SCI data register (SCIxD). 0 No overrun. 1 Receive overrun (new SCI data lost).
2 NF	**Noise Flag** — The advanced sampling technique used in the receiver takes seven samples during the start bit and three samples in each data bit and the stop bit. If any of these samples disagrees with the rest of the samples within any bit time in the frame, the flag NF will be set at the same time as the flag RDRF gets set for the character. To clear NF, read SCIxS1 and then read the SCI data register (SCIxD). 0 No noise detected. 1 Noise detected in the received character in SCIxD.
1 FE	**Framing Error Flag** — FE is set at the same time as RDRF when the receiver detects a logic 0 where the stop bit was expected. This suggests the receiver was not properly aligned to a character frame. To clear FE, read SCIxS1 with FE = 1 and then read the SCI data register (SCIxD). 0 No framing error detected. This does not guarantee the framing is correct. 1 Framing error.
0 PF	**Parity Error Flag** — PF is set at the same time as RDRF when parity is enabled (PE = 1) and the parity bit in the received character does not agree with the expected parity value. To clear PF, read SCIxS1 and then read the SCI data register (SCIxD). 0 No parity error. 1 Parity error.

9-bit data mode typically is used in conjunction with parity to allow eight bits of data plus the parity in the ninth bit. Or it is used with address-mark wakeup so the ninth data bit can serve as the wakeup bit. In custom protocols, the ninth bit can also serve as a software-controlled marker.

11.3.5.2 Stop Mode Operation

During all stop modes, clocks to the SCI module are halted.

In stop1 and stop2 modes, all SCI register data is lost and must be re-initialized upon recovery from these two stop modes.

No SCI module registers are affected in stop3 mode.

Note, because the clocks are halted, the SCI module will resume operation upon exit from stop (only in stop3 mode). Software should ensure stop mode is not entered while there is a character being transmitted out of or received into the SCI module.

11.3.5.3 Loop Mode

When LOOPS = 1, the RSRC bit in the same register chooses between loop mode (RSRC = 0) or single-wire mode (RSRC = 1). Loop mode is sometimes used to check software, independent of connections in the external system, to help isolate system problems. In this mode, the transmitter output is internally connected to the receiver input and the RxD pin is not used by the SCI, so it reverts to a general-purpose port I/O pin.

11.3.5.4 Single-Wire Mode

When LOOPS = 1, the RSRC bit in the same register chooses between loop mode (RSRC = 0) or single-wire mode (RSRC = 1). Single-wire mode is used to implement a half-duplex serial connection. The receiver is internally connected to the transmitter output and to the TxD pin. The RxD pin is not used and reverts to a general-purpose port I/O pin.

In single-wire mode, the TXDIR bit in SCIxC3 controls the direction of serial data on the TxD pin. When TXDIR = 0, the TxD pin is an input to the SCI receiver and the transmitter is temporarily disconnected from the TxD pin so an external device can send serial data to the receiver. When TXDIR = 1, the TxD pin is an output driven by the transmitter.

Table 12-1. SPI1C1 Field Descriptions (continued)

Field	Description
4 MSTR	**Master/Slave Mode Select** 0 SPI module configured as a slave SPI device 1 SPI module configured as a master SPI device
3 CPOL	**Clock Polarity** — This bit effectively places an inverter in series with the clock signal from a master SPI or to a slave SPI device. Refer to Section 12.4.1, “SPI Clock Formats” for more details. 0 Active-high SPI clock (idles low) 1 Active-low SPI clock (idles high)
2 CPHA	**Clock Phase** — This bit selects one of two clock formats for different kinds of synchronous serial peripheral devices. Refer to Section 12.4.1, “SPI Clock Formats” for more details. 0 First edge on SPSCK occurs at the middle of the first cycle of an 8-cycle data transfer 1 First edge on SPSCK occurs at the start of the first cycle of an 8-cycle data transfer
1 SSOE	**Slave Select Output Enable** — This bit is used in combination with the mode fault enable (MODFEN) bit in SPCR2 and the master/slave (MSTR) control bit to determine the function of the $\overline{SS}$ pin as shown in Table 12-2.
0 LSBFE	**LSB First (Shifter Direction)** 0 SPI serial data transfers start with most significant bit 1 SPI serial data transfers start with least significant bit

Table 12-2. $\overline{SS}$ Pin Function

MODFEN	SSOE	Master Mode	Slave Mode
0	0	General-purpose I/O (not SPI)	Slave select input
0	1	General-purpose I/O (not SPI)	Slave select input
1	0	$\overline{SS}$ input for mode fault	Slave select input
1	1	Automatic $\overline{SS}$ output	Slave select input

NOTE

Ensure that the SPI should not be disabled (SPE=0) at the same time as a bit change to the CPHA bit. These changes should be performed as separate operations or unexpected behavior may occur.

12.3.2 SPI Control Register 2 (SPI1C2)

This read/write register is used to control optional features of the SPI system. Bits 7, 6, 5, and 2 are not implemented and always read 0.

	7	6	5	4	3	2	1	0
R	0	0	0	MODFEN	BIDIROE	0	SPISWAI	SPC0
W								
Reset	0	0	0	0	0	0	0	0

= Unimplemented or Reserved

Figure 12-6. SPI Control Register 2 (SPI1C2)

13.1.3 Block Diagram

Figure 13-2 is a block diagram of the IIC.

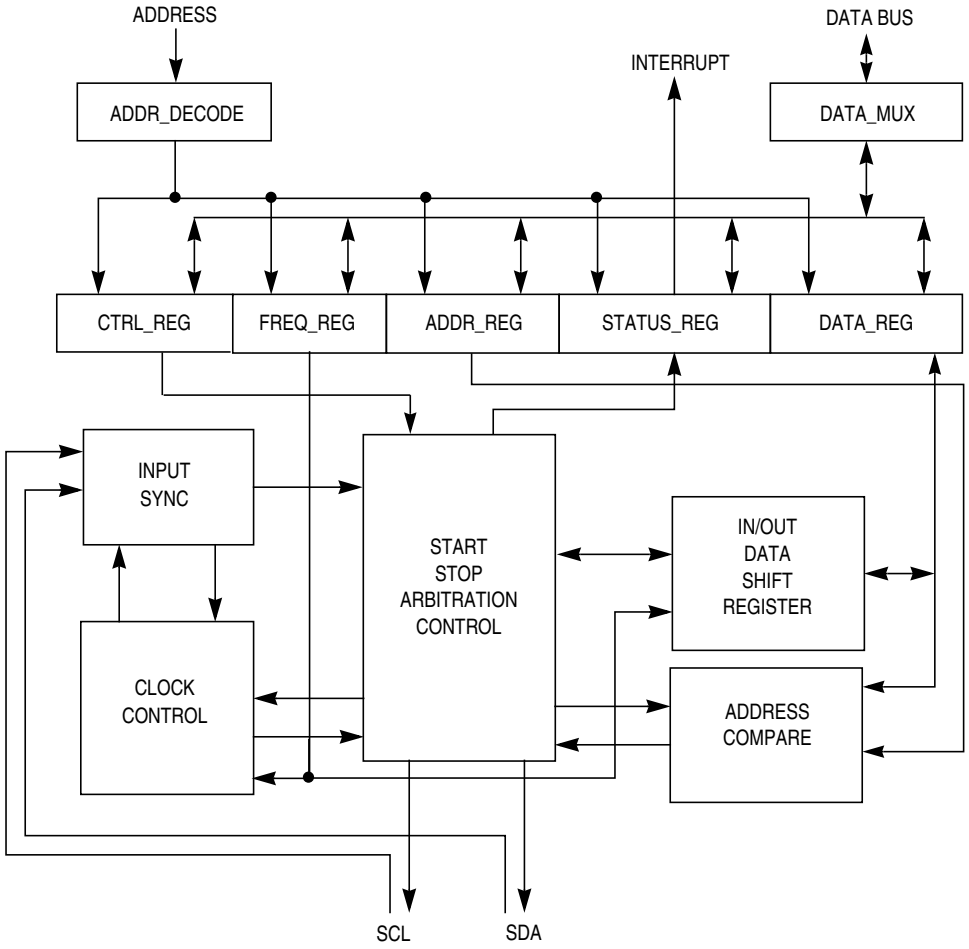


Figure 13-2. IIC Functional Block Diagram

13.2 External Signal Description

This section describes each user-accessible pin signal.

13.2.1 SCL — Serial Clock Line

The bidirectional SCL is the serial clock line of the IIC system.

13.2.2 SDA — Serial Data Line

The bidirectional SDA is the serial data line of the IIC system.

13.3 Register Definition

This section consists of the IIC register descriptions in address order.

13.3.3 IIC Control Register (IIC1C)

	7	6	5	4	3	2	1	0
R	IICEN	IICIE	MST	TX	TXAK	0	0	0
W						RSTA		
Reset	0	0	0	0	0	0	0	0

= Unimplemented or Reserved

Figure 13-5. IIC Control Register (IIC1C)

Table 13-4. IIC1C Register Field Descriptions

Field	Description
7 IICEN	**IIC Enable** — The IICEN bit determines whether the IIC module is enabled. 0 IIC is not enabled. 1 IIC is enabled.
6 IICIE	**IIC Interrupt Enable** — The IICIE bit determines whether an IIC interrupt is requested. 0 IIC interrupt request not enabled. 1 IIC interrupt request enabled.
5 MST	**Master Mode Select** — The MST bit is changed from a 0 to a 1 when a START signal is generated on the bus and master mode is selected. When this bit changes from a 1 to a 0 a STOP signal is generated and the mode of operation changes from master to slave. 0 Slave Mode. 1 Master Mode.
4 TX	**Transmit Mode Select** — The TX bit selects the direction of master and slave transfers. In master mode this bit should be set according to the type of transfer required. Therefore, for address cycles, this bit will always be high. When addressed as a slave this bit should be set by software according to the SRW bit in the status register. 0 Receive. 1 Transmit.
3 TXAK	**Transmit Acknowledge Enable** — This bit specifies the value driven onto the SDA during data acknowledge cycles for both master and slave receivers. 0 An acknowledge signal will be sent out to the bus after receiving one data byte. 1 No acknowledge signal response is sent.
2 RSTA	**Repeat START** — Writing a one to this bit will generate a repeated START condition provided it is the current master. This bit will always be read as a low. Attempting a repeat at the wrong time will result in loss of arbitration.

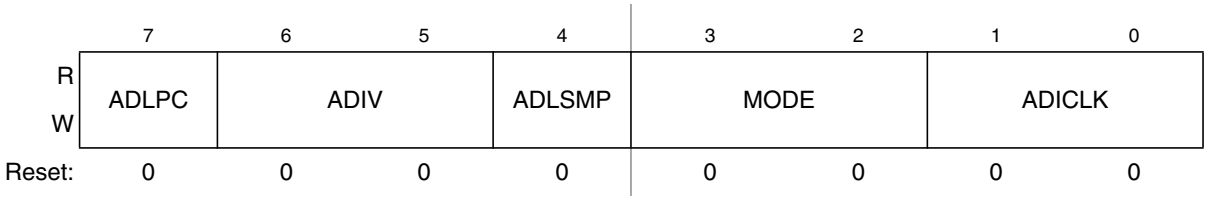


Figure 14-10. Configuration Register (ADC1CFG)

Table 14-5. ADC1CFG Register Field Descriptions

Field	Description
7 ADLPC	**Low Power Configuration** — ADLPC controls the speed and power configuration of the successive approximation converter. This is used to optimize power consumption when higher sample rates are not required. 0 High speed configuration 1 Low power configuration: {FC31}The power is reduced at the expense of maximum clock speed.
6:5 ADIV	**Clock Divide Select** — ADIV select the divide ratio used by the ADC to generate the internal clock ADCK. Table 14-6 shows the available clock configurations.
4 ADLSMP	**Long Sample Time Configuration** — ADLSMP selects between long and short sample time. This adjusts the sample period to allow higher impedance inputs to be accurately sampled or to maximize conversion speed for lower impedance inputs. Longer sample times can also be used to lower overall power consumption when continuous conversions are enabled if high conversion rates are not required. 0 Short sample time 1 Long sample time
3:2 MODE	**Conversion Mode Selection** — MODE bits are used to select between 10- or 8-bit operation. See Table 14-7.
1:0 ADICLK	**Input Clock Select** — ADICLK bits select the input clock source to generate the internal clock ADCK. See Table 14-8.

Table 14-6. Clock Divide Select

ADIV	Divide Ratio	Clock Rate
00	1	Input clock
01	2	Input clock ÷ 2
10	4	Input clock ÷ 4
11	8	Input clock ÷ 8

Table 14-7. Conversion Modes

MODE	Mode Description
00	8-bit conversion (N=8)
01	Reserved
10	10-bit conversion (N=10)
11	Reserved

The SYNC command is unlike other BDC commands because the host does not necessarily know the correct communications speed to use for BDC communications until after it has analyzed the response to the SYNC command.

To issue a SYNC command, the host:

- Drives the BKGD pin low for at least 128 cycles of the slowest possible BDC clock (The slowest clock is normally the reference oscillator/64 or the self-clocked rate/64.)
- Drives BKGD high for a brief speedup pulse to get a fast rise time (This speedup pulse is typically one cycle of the fastest clock in the system.)
- Removes all drive to the BKGD pin so it reverts to high impedance
- Monitors the BKGD pin for the sync response pulse

The target, upon detecting the SYNC request from the host (which is a much longer low time than would ever occur during normal BDC communications):

- Waits for BKGD to return to a logic high
- Delays 16 cycles to allow the host to stop driving the high speedup pulse
- Drives BKGD low for 128 BDC clock cycles
- Drives a 1-cycle high speedup pulse to force a fast rise time on BKGD
- Removes all drive to the BKGD pin so it reverts to high impedance

The host measures the low time of this 128-cycle sync response pulse and determines the correct speed for subsequent BDC communications. Typically, the host can determine the correct communication speed within a few percent of the actual target speed and the communication protocol can easily tolerate speed errors of several percent.

15.2.4 BDC Hardware Breakpoint

The BDC includes one relatively simple hardware breakpoint that compares the CPU address bus to a 16-bit match value in the BDCBKPT register. This breakpoint can generate a forced breakpoint or a tagged breakpoint. A forced breakpoint causes the CPU to enter active background mode at the first instruction boundary following any access to the breakpoint address. The tagged breakpoint causes the instruction opcode at the breakpoint address to be tagged so that the CPU will enter active background mode rather than executing that instruction if and when it reaches the end of the instruction queue. This implies that tagged breakpoints can only be placed at the address of an instruction opcode while forced breakpoints can be set at any address.

The breakpoint enable (BKPTEN) control bit in the BDC status and control register (BDCSCR) is used to enable the breakpoint logic (BKPTEN = 1). When BKPTEN = 0, its default value after reset, the breakpoint logic is disabled and no BDC breakpoints are requested regardless of the values in other BDC breakpoint registers and control bits. The force/tag select (FTS) control bit in BDCSCR is used to select forced (FTS = 1) or tagged (FTS = 0) type breakpoints.

The on-chip debug module (DBG) includes circuitry for two additional hardware breakpoints that are more flexible than the simple breakpoint in the BDC module.

Table A-2. Absolute Maximum Ratings

Rating	Symbol	Value	Unit
Supply voltage	V_{DD}	−0.3 to + 5.8	V
Input voltage	V_{In}	− 0.3 to V_{DD} + 0.3	V
Instantaneous maximum current Single pin limit (applies to all port pins)[1], [2], [3]	I_D	± 25	mA
Maximum current into V_{DD}	I_{DD}	120	mA
Storage temperature	T_{stg}	−55 to +150	°C
Maximum junction temperature	T_J	150	°C

1 Input must be current limited to the value specified. To determine the value of the required current-limiting resistor, calculate resistance values for positive (V_{DD}) and negative (V_{SS}) clamp voltages, then use the larger of the two resistance values.

2 All functional non-supply pins are internally clamped to V_{SS} and V_{DD}.

3 Power supply must maintain regulation within operating V_{DD} range during instantaneous and operating maximum current conditions. If positive injection current (V_{In} > V_{DD}) is greater than I_{DD}, the injection current may flow out of V_{DD} and could result in external power supply going out of regulation. Ensure external V_{DD} load will shunt current greater than maximum injection current. This will be the greatest risk when the MCU is not consuming power. Examples are: if no system clock is present, or if the clock rate is very low which would reduce overall power consumption.

Solving equations 1 and 2 for K gives:

$$K = P_D \times (T_A + 273°C) + \theta_{JA} \times (P_D)^2 \qquad \textit{Eqn. A-3}$$

where K is a constant pertaining to the particular part. K can be determined from equation 3 by measuring P_D (at equilibrium) for a known T_A. Using this value of K, the values of P_D and T_J can be obtained by solving equations 1 and 2 iteratively for any value of T_A.

A.5 ESD Protection and Latch-Up Immunity

Although damage from electrostatic discharge (ESD) is much less common on these devices than on early CMOS circuits, normal handling precautions should be used to avoid exposure to static discharge. Qualification tests are performed to ensure that these devices can withstand exposure to reasonable levels of static without suffering any permanent damage.

All ESD testing is in conformity with AEC-Q100 Stress Test Qualification for Automotive Grade Integrated Circuits. During the device qualification ESD stresses were performed for the Human Body Model (HBM), the Machine Model (MM) and the Charge Device Model (CDM).

A device is defined as a failure if after exposure to ESD pulses the device no longer meets the device specification. Complete DC parametric and functional testing is performed per the applicable device specification at room temperature followed by hot temperature, unless specified otherwise in the device specification.

Table A-4. ESD and Latch-up Test Conditions

Model	Description	Symbol	Value	Unit
Human Body Model	Series Resistance	R1	1500	Ω
	Storage Capacitance	C	100	pF
	Number of Pulse per pin	—	3	
Machine Model	Series Resistance	R1	0	Ω
	Storage Capacitance	C	200	pF
	Number of Pulse per pin	—	3	
Latch-Up	Minimum input voltage limit		–2.5	V
	Maximum input voltage limit		7.5	V

Table A-5. ESD and Latch-Up Protection Characteristics

Num	C	Rating	Symbol	Min	Max	Unit
1	C	Human Body Model (HBM)	V_{HBM}	± 2000	—	V
2	C	Machine Model (MM)	V_{MM}	± 200	—	V
3	C	Charge Device Model (CDM)	V_{CDM}	± 500	—	V
4	C	Latch-up Current at T_A = 125°C	I_{LAT}	± 100	—	mA

Appendix B
Ordering Information and Mechanical Drawings

B.1 Ordering Information

This section contains ordering numbers for MC9S08AW60 Series devices. See below for an example of the device numbering system.

Table B-1. *Consumer and Industrial* Device Numbering System

Device Number[1]	Memory		Available Packages[2]
	FLASH	RAM	Type
MC9S08AW60 MC9S08AW48 MC9S08AW32	63,280 49,152 32,768	2048	64-pin LQFP 64-pin QFP 48-pin QFN 44-pin LQFP
MC9S08AW16	16,384	1024	

1 See Table 1-1 for a complete description of modules included on each device.

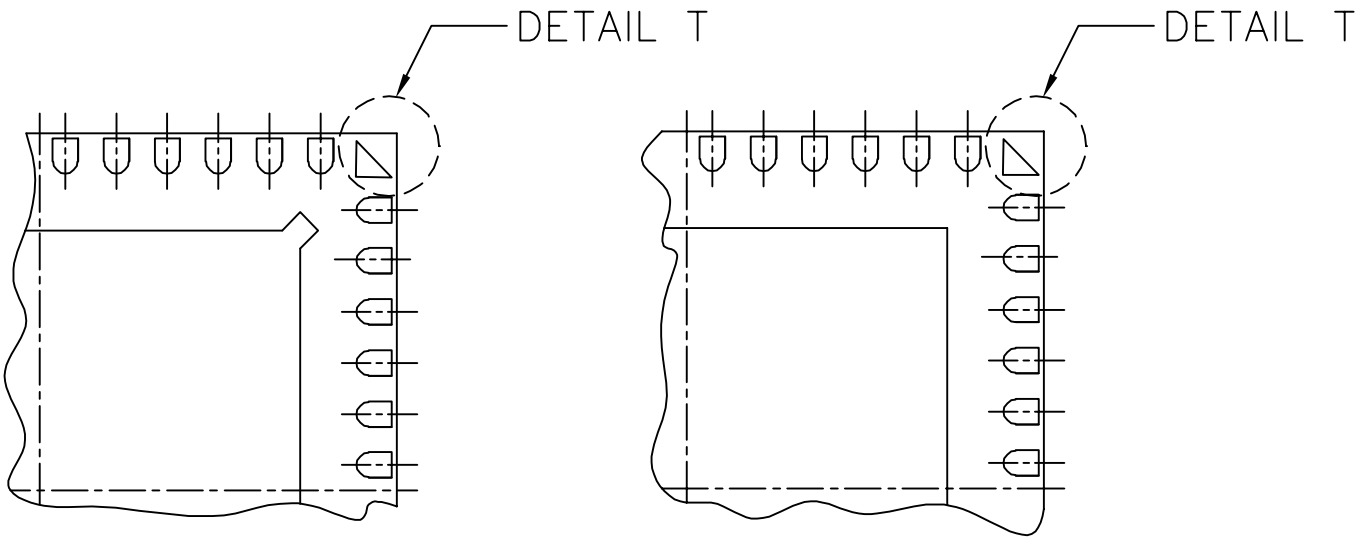
2 See Table B-3 for package information.

Table B-2. *Automotive* Device Numbering System

Device Number[1]	Memory		Available Packages[2]
	FLASH	RAM	Type
S9S08AW60 S9S08AW48 S9S08AW32	63,280 49,152 32,768	2048	64-pin LQFP 48-pin QFN 44-pin LQFP
S9S08AW16	16,384	1024	48-pin QFN 44-pin LQFP

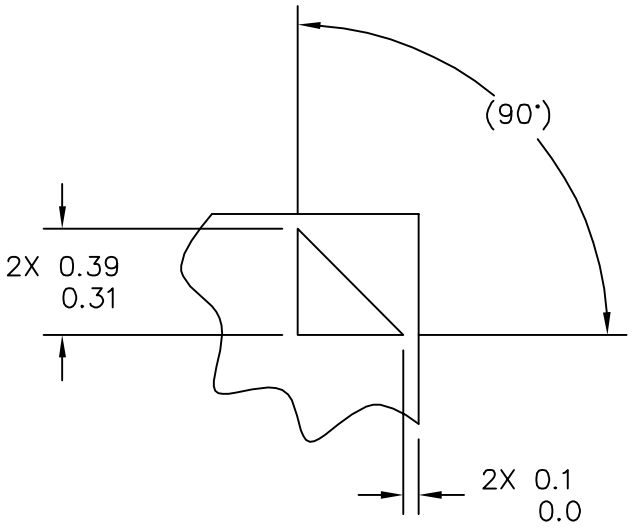
1 See Table 1-1 for a complete description of modules included on each device.

2 See Table B-3 for package information.



DETAIL M
PIN 1 BACKSIDE IDENTIFIER OPTION

DETAIL M
PIN 1 BACKSIDE IDENTIFIER OPTION



DETAIL T

MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE

TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 48 TERMINAL, 0.5 PITCH (7 X 7 X 1)	DOCUMENT NO: 98ARH99048A	REV: F
	CASE NUMBER: 1314-05	05 DEC 2005
	STANDARD: JEDEC-MO-220 VKKD-2	